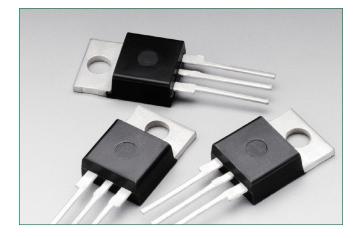
Po

MCR8SDG, MCR8SMG, MCR8SNG Sensitive Gate Silicon <u>Controlled Rectifiers</u> — 400V - 800V



Additional Information







Resources

Functional Diagram

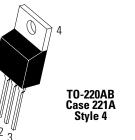


Description

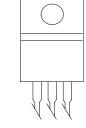
Designed primarily for half-wave ac control applications, such as motor controls, heating controls, and power supplies; or wherever half-wave, silicon gate-controlled devices are needed.

Features

- Sensitive Gate Allows Triggering by Microcontrollers and other Logic Circuits
- Blocking Voltage to 800 V
- On-State Current Rating of 8 A RMS at 80°C
- High Surge Current Capability
 80 A
- Rugged, Economical TO-220AB Package
- Glass Passivated Junctions for Reliability and Uniformity
- Minimum and Maximum Values of IGT, VGT and IH Specified for Ease of Design
- Immunity to dv/dt 5 V/µsec Minimum at 110°C
- These are Pb-Free Devices



Pin Out





Maximum Ratings ($T_{J} = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit	
Peak Repetitive Off-State Voltage (Note 1) (- 40 to 110°C, Sine Wave, 50 to 60 Hz, Gate Open)	V _{drm} , V _{rrm}	400 600 800	V	
On-State RMS Current (180° Conduction Angles; $T_c = 80$ °C)		I _{T (RMS)}	8.0	А
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T _J = 110°C)	I _{TSM}	80	А	
Circuit Fusing Consideration (t = 8.33 ms)	l²t	26.5	A ² sec	
Forward Peak Gate Power (Pulse Width \leq 10 $\mu sec, T_{_{\rm C}}$ = 80°C)	P _{GM}	5.0	W	
Forward Average Gate Power (t = 8.3 msec, $T_c = 80^{\circ}$ C)	P _{GM (AV)}	0.5	W	
Forward Peak Gate Current (Pulse Width \leq 10 $\mu sec,$ $T_c =$ 80°C)	I _{GM}	2.0	А	
Operating Junction Temperature Range	TJ	-40 to 110	°C	
Storage Temperature Range	T _{stg}	-40 to 150	°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. V_{DBM} and V_{RBM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Thermal Characteristics

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R _{sJC}	2.2	°C/W
Thermal Resistance, Junction-to-Ambient	R _{8JA}	62.5	C/VV
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

Electrical Characteristics - OFF ($T_J = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Мах	Unit
Peak Repetitive Forward or Reverse Blocking Current (Note 3)	$T_{J} = 25^{\circ}C$	I _{DRM} ,	-	-	10	
$(V_{AK} = Rated V_{DRM} \text{ or } V_{RRM'} R_{GK} = 1.0 \text{ k}\Omega$	T _J = 110°C	I	-	-	500	μA

Electrical Characteristics - ON (T_J = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Forward On–State Voltage (Note 2) ($I_{TM} = 16 A$)		V _{TM}	-	-	1.8	V
Gate Trigger Current (Continuous dc) (Note 4) ($V_p = 12 \text{ V}; \text{ R}_1 = 100 \Omega$)		I _{gt}	5.0	25	200	μΑ
Holding Current (Note 3) ($V_p = 12$ V, Gate Open, Initiating Current = 200 mA)		I _H	-	0.5	6.0	mA
Latch Current (Note 4) ($V_p = 12 \text{ V}, I_g = 200 \mu\text{A}$)		I _L	-	0.6	8.0	mA
Gate Trigger Voltage (Continuous dc) ($V_p = 12 \text{ V}, \text{ R}_1 = 100 \Omega$)	T_ = 25°C	V	0.3	0.65	1.0	V
(Note 4)	$T_{J} = -40^{\circ}C$	V _{gt}	-	-	1.5	V
Gate Non-Trigger Voltage ($V_D = 12 V, R_L = 100 \Omega$)	$T_{_{\rm J}} = 110^{\circ}{\rm C}$	V_{gd}	0.2	-	-	V



Dynamic Characteristics

Characteristic	Symbol	Min	Тур	Мах	Unit
Critical Rate of Rise of Off–State Voltage ($V_D = 67\% V_{DRM}$, $R_{GK} = 1 K\Omega$, $C_{GK} = 0.1 \mu$ F, $T_J = 110^{\circ}$ C)	dv/dt	5.0	15	-	V/µs
Critical Rate of Rise of On-State Current (IPK = 50 A, Pw = 40 µsec, diG/dt = 1 A/µsec, Igt = 10 mA	di/dt	-	-	100	A/µs

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

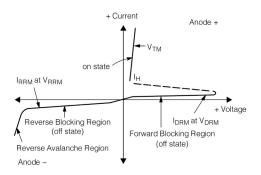
2. Ratings apply for negative gate voltage or RGK = 1.0 kQ. Devices shall not have a positive gate voltage concurrently with a negative voltage on the anode. Devices should not be tested with a constant current source for forward and reverse blocking capability such that the voltage applied exceeds the rated blocking voltage.

3. Pulse Test; Pulse Width \leq 2.0 msec, Duty Cycle \leq 2%.

4. RGK current not included in measurements.

Voltage Current Characteristic of SCR

Symbol	Parameter		
V _{DRM}	Peak Repetitive Forward Off State Voltage		
I _{DRM}	Peak Forward Blocking Current		
V _{RRM}	Peak Repetitive Reverse Off State Voltage		
I _{RRM}	Peak Reverse Blocking Current		
V _{TM}	Maximum On State Voltage		
I _H	Holding Current		



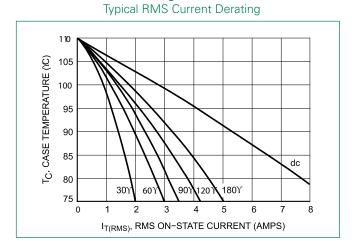
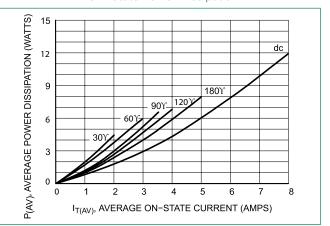


Figure 1.

Figure 2. On–State Power Dissipation



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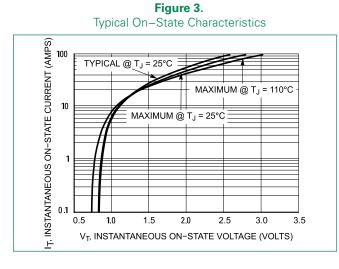


Figure 5. Typical Gate Trigger Current vs Junction Temperature

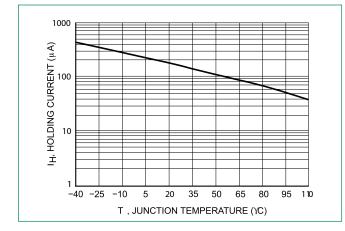
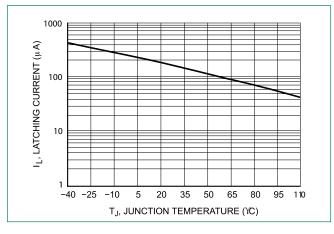


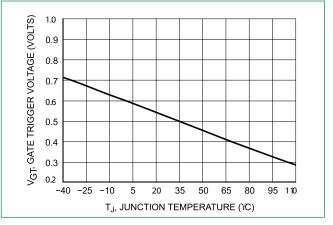
Figure 7. Typical Holding Current vs Junction Temperature



100 GATE TRIGGER CURRENT (μA) 90 80 70 60 50 40 30 20 10 0 -40 -25 -10 5 20 35 50 65 80 95 110 TJ, JUNCTION TEMPERATURE (YC)

Figure 4. Typical Gate Trigger Current vs Junction Temperature



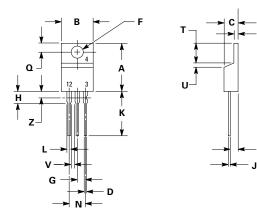




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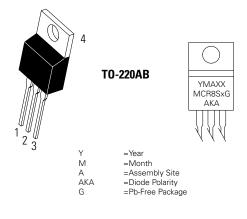
S

R



Dimensions

Part Marking System



	Inches		Millin	neters
Dim	Min	Мах	Min	Max
Α	0.590	0.620	14.99	15.75
В	0.380	0.420	9.65	10.67
С	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.41	2.67
н	0.110	0.130	2.79	3.30
J	0.018	0.024	0.46	0.61
К	0.540	0.575	13.72	14.61
L	0.060	0.075	1.52	1.91
Ν	0.195	0.205	4.95	5.21
Q	0.105	0.115	2.67	2.92
R	0.085	0.095	2.16	2.41
S	0.045	0.060	1.14	1.52
т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

Pin Assignment				
1	Cathode			
2	Anode			
3	Gate			
4 Anode				

Ordering Information

Device	Package	Shipping		
MCR8SDG				
MCR8SMG	TO-220AB (Pb-Free)	1000 Units / Box		
MCR8SNG	(1.2.1.00)			

1. Dimensioning and tolerancing per ansi y14.5m, 1982.

Controlling dimension inch.
 Dimension z defines a zone where all body and lead irregularities are allowed.

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 T1220N22TOF VT
 T201N70TOH
 T700N22TOF
 T830N18TOF
 TT250N12KOF-K
 VS-16RIA120
 VS-110RKI40
 NTE5427
 NTE5442

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 VS-22RIA100
 VS-16RIA40
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 NTE5592
 NTE5598